

• General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

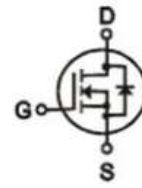
• Features

- Advance device constructure
- Low $R_{DS(ON)}$ to minimize conduction loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- Synchronous Rectification for AC-DC/DC-DC converter
- Power Tools

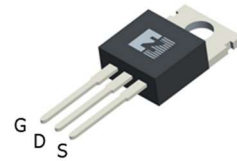
• Product Summary



$$V_{DS} = 120V$$

$$R_{DS(ON)} = 12m\Omega$$

$$I_D = 80A$$



TO-220

• Ordering Information:

Part NO.	ZMS110N12HP
Marking	ZMS110N12H
Packing Information	Bulk Tube
Basic ordering unit (pcs)	1000

• Absolute Maximum Ratings ($T_c = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	120	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_{D@TC=25^\circ C}$	80	A
	$I_{D@TC=75^\circ C}$	60	A
	$I_{D@TC=100^\circ C}$	50	A
Pulsed Drain Current ^①	I_{DM}	240	A
Total Power Dissipation($TC=25^\circ C$)	$P_D@TC=25^\circ C$	125	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy@ $L=0.1mH$	E_{AS}	80	mJ
Avalanche Current@ $L=0.1mH$	I_{AS}	40	A

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.0	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	62	° C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	120			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	2.0		4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 100V, V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 30A$		12	15	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 40A$		18		s
Diode Forward Voltage	V_{FSD}	$I_S = 30A$			1.2	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$V_{DS} = 25V$ $f = 1MHz$	-	2420	-	pF
Output capacitance	C_{oss}		-	960	-	
Reverse transfer capacitance	C_{rss}		-	54	-	

•Switching Parameters ($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD} = 15V$ $I_D = 30A$ $V_{GS} = 10V$	-	28	-	nC
Gate - Source charge	Q_{gs}		-	3.8	-	
Gate - Drain charge	Q_{gd}		-	5.9	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS} = 10V,$ $V_{DS} = 50V,$ $R_L = 0.75\Omega,$ $R = 6\Omega$		15		ns
Turn-ON Rise time	t_r			17		
Turn-Off Delay time	$t_{D(off)}$			96		
Turn-Off Fall time	t_f			76		

Body Diode Reverse Recovery Time	t_{rr}	IF=20A, dI/dt=100A/μs		56		ns
Body Diode Reverse Recovery Charge	Q_{rr}	IF=20A, dI/dt=100A/μs		38		nC

Note: ① Pulse Test : Pulse width ≤ 10μs, Duty cycle ≤ 1% ;

Fig.1 Gate-Charge Characteristics

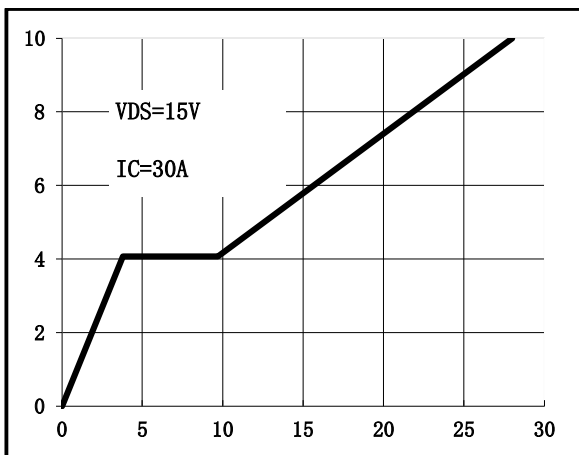


Fig.2 Capacitance Characteristics

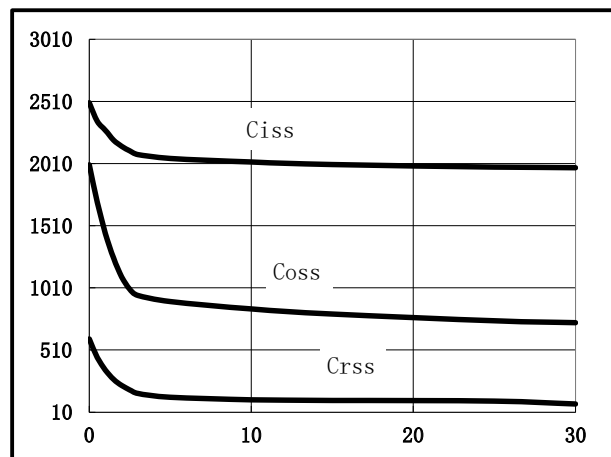


Fig.3 Power Dissipation

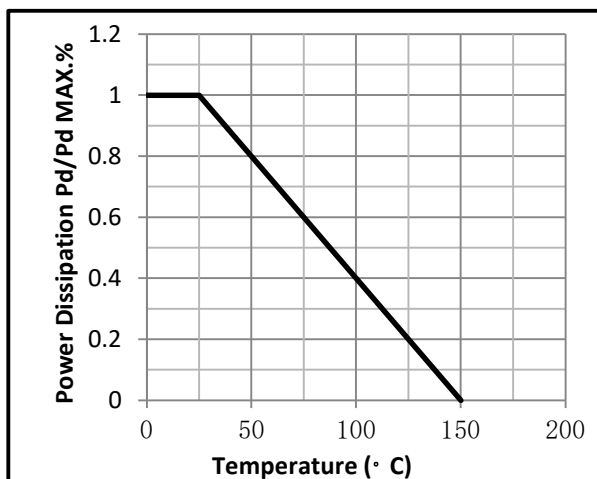


Fig.4 Typical output Characteristics

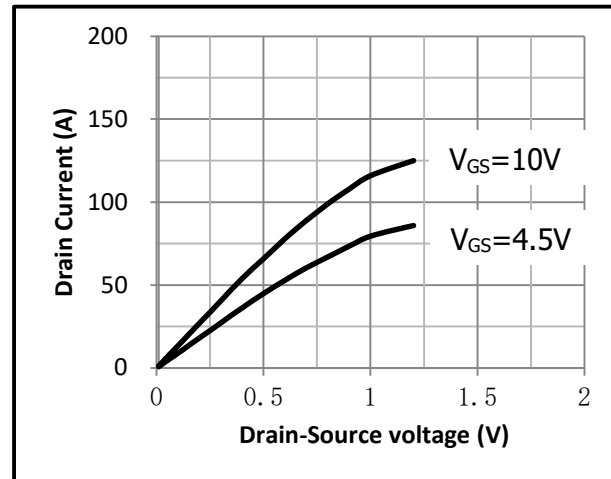


Fig.5 Threshold Voltage V.S Junction Temperature Fig.6 Resistance V.S Drain Current

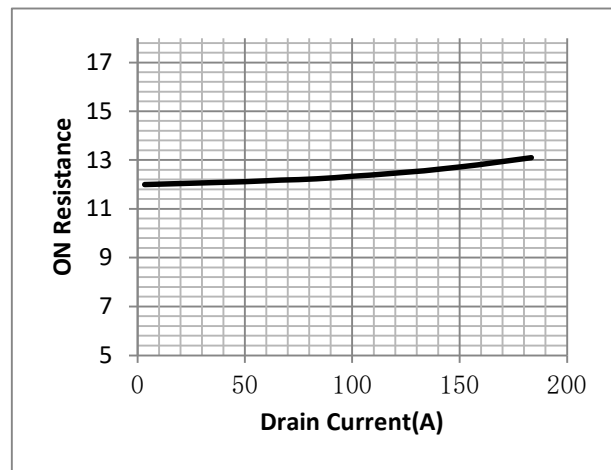
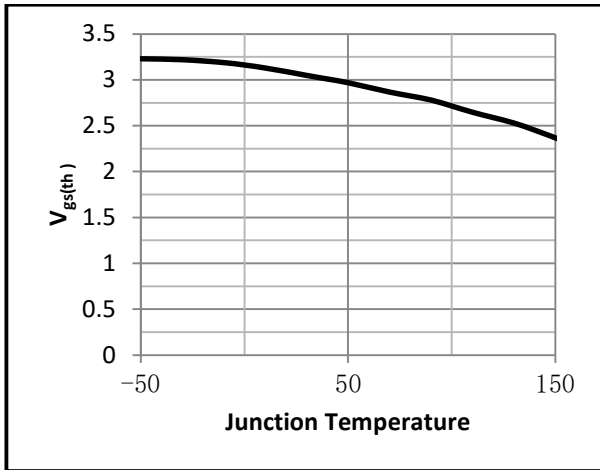


Fig.7 On-Resistance VS Gate Source Voltage

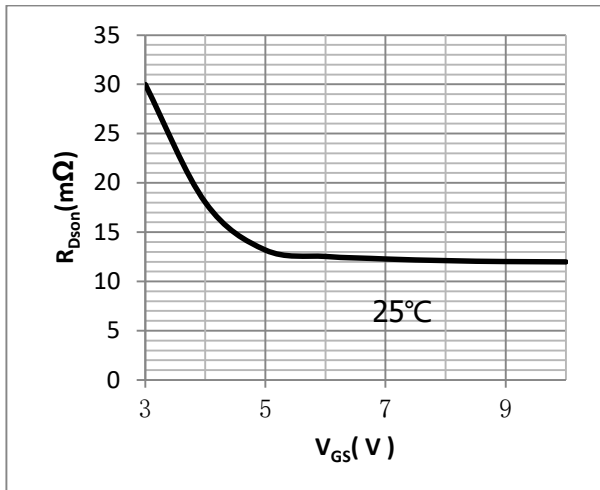


Fig.8 On-Resistance V.S Junction Temperature

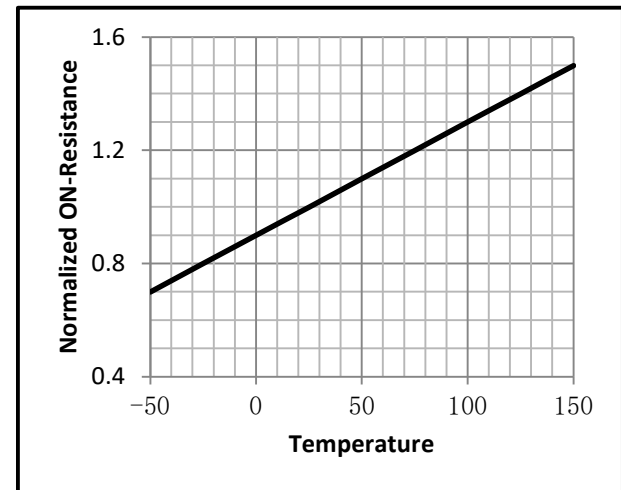


Fig.9 Gate Charge Measurement Circuit

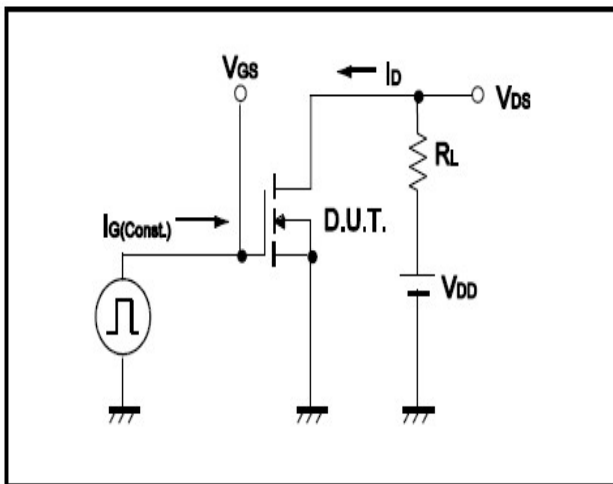


Fig.10 Gate Charge Waveform

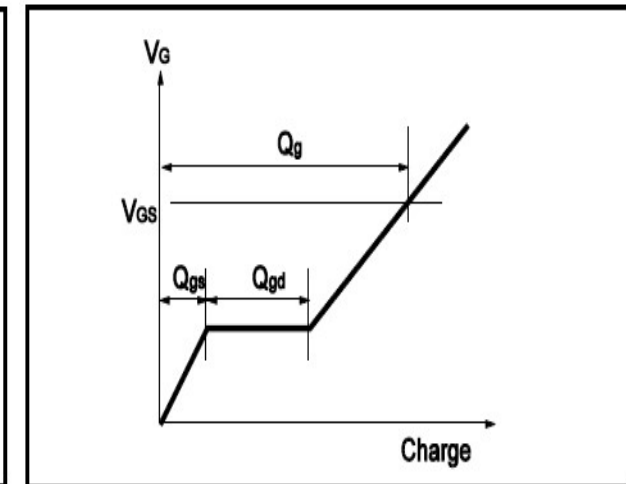


Fig.11 Switching Time Measurement Circuit

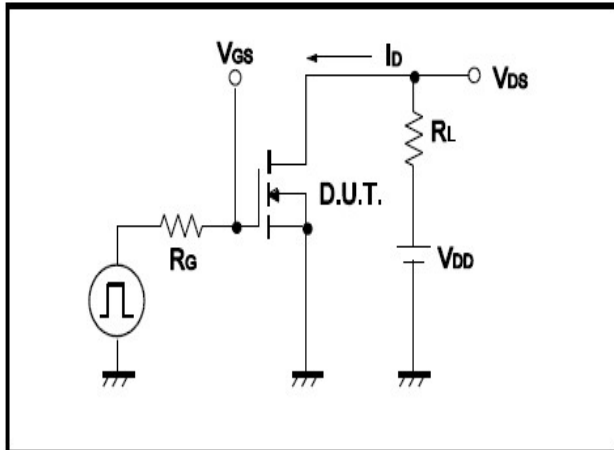
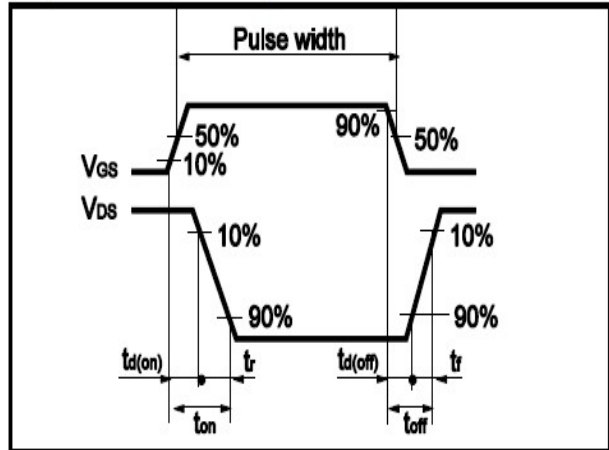


Fig.12 Switching Time Waveform



• **Dimensions (TO-220)**

Unit: mm

SYMBOL	min	nom	max	SYMBOL	min	nom	max
A	4.00		4.80	E	9.90		10.70
B	1.20		1.50	e		2.54	
B1	1.00		1.40	F	1.10		1.45
b1	0.65		1.00	L	12.50		14.50
c	0.35		0.75	L1	3.00	3.50	4.00
D	15.00		16.50	Q	2.50		3.00
D1	5.90		6.90	Q1	2.00		3.00
				ΦP	3.60		3.90

